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--47. The modification method of the resin surface layer according to claim 7 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.--

--48. The modification method of the resin surface layer according to claim 8 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.--

--49. The modification method of the resin surface layer according to claim 9 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.--

--50. The modification method of the resin surface layer according to claim 10 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.

--51. The modification method of the resin surface layer according to claim 11 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.--

--52. The modification method of the resin surface layer according to claim 12 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

in order to allow the deposited organic compound to penetrate/disperse for the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition of the organic compound and/or the resin.--

--53. The modification method of the resin surface layer according to claim 46

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--54. The modification method of the resin surface layer according to claim 47

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--55. The modification method of the resin surface layer according to claim 48

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--56. The modification method of the resin surface layer according to claim 49

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--57. The modification method of the resin surface layer according to claim 50

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--58. The modification method of the resin surface layer according to claim 51

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--59. The modification method of the resin surface layer according to claim 52

wherein:

a dyestuff having the sublimation properties and the affinity for the resin of the molded resin article to be coated is used as the organic compound to modify and simultaneously color the surface layer of the molded resin article.--

--60. The modification apparatus of the resin surface layer according to claim 18

which further contains:

a stirring mechanism for stirring the molded resin article of a powder form.--

--61. The modification apparatus of the resin surface layer according to claim 18

which further contains:

a wind-up mechanism for winding up the molded resin article of a form selected from a textile form, a fiber form and film form around a reception side reel from a supply side reel under reduced pressure.--

--62. The coloring apparatus of the resin surface layer according to claim 23 which further contains:

a stirring mechanism for stirring the molded resin article of a powder form.--

--63. The coloring apparatus of the resin surface layer according to claim 23 which further contains:

a wind-up mechanism for winding up the molded resin article of a form selected from a textile form, a fiber form and film form around a reception side reel from a supply side reel under reduced pressure.--